

ABSTRACT

SUBSTRATE ALIGNMENT METHOD AND APPARATUS

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The invention provides a method and apparatus for aligning a substrate. The apparatus comprises a ball pick head for picking up a plurality of solder balls in a ball pick-up process and depositing them onto the substrate, and a vision system adapted to view and obtain positional information of the substrate.

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Furthermore, a carrier is provided to which the vision system is mountable, such that operation of the vision system is decoupled from movement of the ball pick head. Drivers responsive to said positional information viewed by the vision system are operative to align at least the substrate and the ball pick head for depositing solder balls onto the substrate.

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(Figure 3)